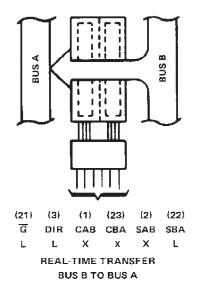
SDLS190A - DECEMBER 1982 - REVISED MAY 2004

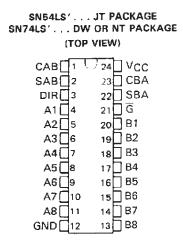
- · Independent Registers for A and B Buses
- Multiplexed Real-Time and Stored Data
- Choice of True or Inverting Data Paths
- Choice of 3-State or Open-Collector Outputs
- Included Among the Package Options Are Compact 24-pin 300-mil-Wide Plastic and Ceramic DIPs, Ceramic Chip Carriers, and Plastic "Small Outline" Packages
- Dependable Texas Instruments Quality and Reliability

DEVICE	OUTPUT	LOGIC
'L\$646	3-State	True
'L\$647	Open-Collector	True
'LS648	3-State	Inverting
'LS649	Open-Collector	Inverting

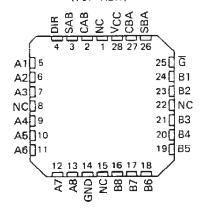
### description

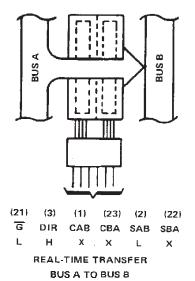
These devices consist of bus transceiver circuits with 3-state or open-collector outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus will be clocked into the registers on the low-to-high transition of the appropriate clock pin (CAB or CBA). The following examples demonstrate the four fundamental bus-management functions that can be performed with the octal bus transceivers and registers.





SN54LS'...FK PACKAGE (TOP VIEW)





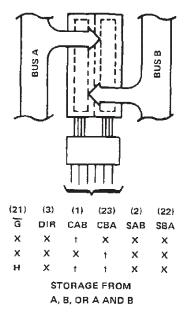


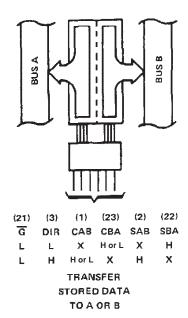
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



# SN54LS646 THRU SN54LS649, SN74LS646 THRU SN74LS649 OCTAL BUS TRANSCEIVERS AND REGISTERS

SDLS190A - DECEMBER 1982 - REVISED MAY 2004





Enable (G) and direction (DIR) pins are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select controls (SAB and SBA) can multiplex stored and real-time (transparent mode) data. The direction control determines which bus will receive data when enable  $\overline{G}$  is active (low). In the isolation mode (control  $\overline{G}$  high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

The SN54' family is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74' family is characterized for operation from 0° to 70°C.

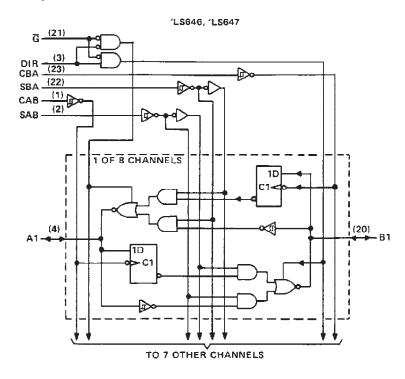
### **FUNCTION TABLE**

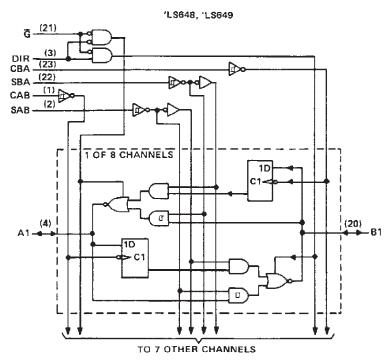
	•••	INPUT	rs			DATA	4 I/O <sup>†</sup>	OPERATION OR FUNCTION			
G	DIR	ÇAB	CBA	SAB	SBA	A1 THRU A8 B1 THRU B8		LS646, LS647	LS648, LS649		
×	Х	†	×	X	Х	Input	Not specified	Store A, B unspecified	Store A, B unspecified		
×	X	x	, †	Х	Х	Not specified	Input	Stare B, A unspecified	Store B, A unspecified		
H	Х	t	†	Х	Х			Store A and B Data	Store A and B Data		
Н	Х	H or L	HorL	Х	Х	Input	Input	Isolation, hold storage	Isolation, hold storage		
L	L	Х	Х	X	L	8		Reat-Time 8 Data to A Bus	Real-Time B Data to A Bus		
L	L	Х	H or L	Х	Η	Output Input		Stored B Data to A Bus	Stored B Data to A Bus		
L	н	Х	X	L	×	Input Output		Real-Time A Data to B Bus	Real-Time A Data to B Bus		
L_	Н	H or L	X	Н	X			Stored A Data to B Bus	Stored A Data to B Bus		

 $<sup>^{\</sup>dagger}$  The data output functions may be enabled or disabled by various signals at the  $\overline{G}$  and DIR inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.



### logic diagrams (positive logic)

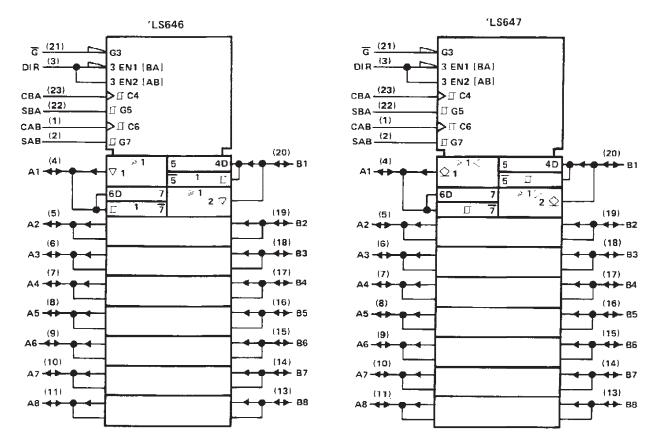




Pin numbers shown are for DW, JT, and NT packages.



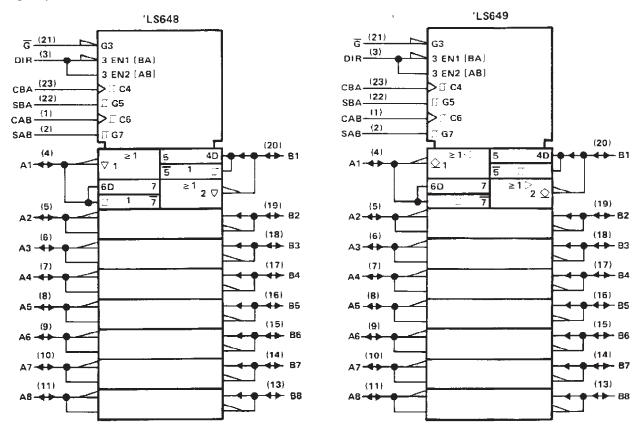
### logic symbols†



 $<sup>^\</sup>dagger$ These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, JT, and NT packages.



### logic symbols † (continued)

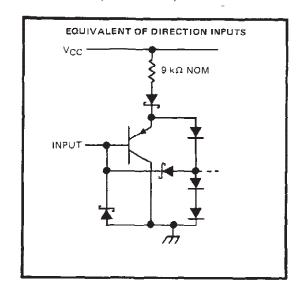


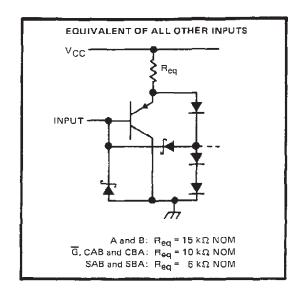
 $<sup>^\</sup>dagger$ These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, JT, and NT packages.

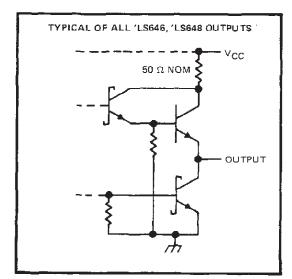


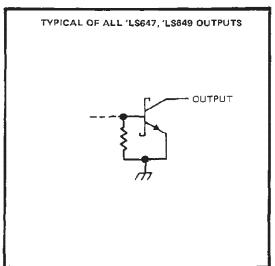
SDLS190A - DECEMBER 1982 - REVISED MAY 2004

### schematics of inputs and outputs









# SN54LS646, SN54LS648, SN74LS646, SN74LS648 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SDLS190A - DECEMBER 1982 - REVISED MAY 2004

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC			7 V
Input voltage: Control inputs			7 V
1/0 ports			5.5 V
Operating free-air temperature range:	SN54LS646, SN54LS648		– 55°C to 125°C
	SN74LS646, SN74LS648	· · · · · · · · · · · · · · · · · · ·	
Storage temperature range			— 65°C to 150°C

### recommended operating conditions

			SN54LS646/648			SN74LS646/648			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	ONT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
$V_{IH}$	High-level input voltage		2			2			V
VIL	Low-lever input voltage			-	0.5			0.6	V
ф	High-level output current				- 12			- 15	mΑ
IOL	Low-level output current				12			24	mA
	Pulse duration	CBA or CAB high	15			15			
t <sub>w</sub>		CBA or CAB low	30			30			ns
		Data high or low	30			30		•	
	Setup time	A == 0							
t <sub>su</sub>	before CAS1 or CBA1	A or B	15			15			ns
	Hold time	A - B							
th	after CAB† or CBA†	A or B	0		1	0			ns
Тд	Operating free-air temperature		- 55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDIT	lowet	SN5	i4LS646	/648	SN7	4LS646	/648	UNIT	
PARAN	IETEK	TEST CONDITIONS				TYP‡	MAX	MIN	TYP‡	MAX	UNII	
VIK		V <sub>CC</sub> = MIN,	I <sub>i</sub> = — 18 mA				- 1.5			- 1.5	V	
Hysteresis	A or B	VCC = MIN			0.1	0.4		0.2	0.4		٧	
		V <sub>CC</sub> = MIN,	V = 2 V	I <sub>OH</sub> = -3 mA	2.4	3.4		2.4	3.4			
∨он		VIL = MAX	VIH - 2 V,	I <sub>OH</sub> = - 12 mA	2						V	
		VIL = WIAA		I <sub>OH</sub> = - 15 mA				2	1 11 11			
Vol		VCC = MIN,	$V_{IH} = 2 V$ ,	I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	v	
- VOL		V <sub>IL</sub> = MAX		I <sub>OL</sub> = 24 mA					0.35	0.5	· · ·	
I <sub>I</sub>	Control inputs	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mΑ	
'I	A or B parts	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 5.5 V				0.1			0.1	13115	
<sup>1</sup> 1H	Control inputs	V <sub>CC</sub> = MAX,	V. = 27 V			_	20			20	μА	
'IH	A or B ports	· CC MAX,	V 2., V	V   - 2.7 V			20			20	μΑ.	
IIL	Control inputs	Voc = MAX	V1 = 0.4 V				-0.4			- 0.4	mA	
-16	A or B ports	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V					- 0.4			0.4	IIIA	
los §		V <sub>CC</sub> = MAX,	VO = 0 V		<b>– 40</b>		<b>- 225</b>	- 40		- 225	mΑ	
				Outputs high		91	145		91	145		
	∟\$646			Outputs low		103	165		103	165		
¹cc		Vcc = MAX		Outputs disabled		103	165	<u> </u>	103	165	mA	
-00		, CC IIIAX		Outputs high		91	145		91	145		
	L5648			Outputs low		103	165		103	165		
				Outputs disabled		120	180		120	180		

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



<sup>&</sup>lt;sup>‡</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25 °C.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

 $<sup>\</sup>P$  For I/O ports, the parameters  $I_{\mbox{\scriptsize IH}}$  and  $I_{\mbox{\scriptsize IL}}$  include the off-state output current.

# SN54LS646, SN54LS648, SN74LS646, SN74LS648 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS SDLS190A - DECEMBER 1982 - REVISED MAY 2004

# switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

	FROM	то		′LS6	46	'L\$648		
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN TY	P MAX	MIN TYP	MAX	UNIT
<sup>t</sup> PLH	CAB or CBA	A or B		1	5 25	15	25	ns
tPHL	CAD OF CDA	A Ur B		2	3 35	24	40	ns
tPLH	A or B	B or A		1	2 18	12	18	ns
tPHL.	AOIB	B 01 X		1	3 20	15	25	กร
₹PLH	SAB or SBA <sup>†</sup> with Bus			2	6 40	37	55	ns
tPHL	input high	A or B	R <sub>L</sub> = 667 Ω, C <sub>L</sub> = 45 pF,	2	1 35	24	40	กร
<sup>t</sup> PLH	SAB or SBA <sup>†</sup> with Bus		See Note 2	33 50	3 50	26	40	ns
<sup>†</sup> PHL	input low			1	4 25	23	40	nş
<sup>t</sup> PZH	<u> </u>			3	3 55	30	50	ns
<sup>t</sup> PZL	]	AorB		4	2 65	37	55	ns
<sup>t</sup> PZH	DIE.	AUIB		2	8 45	23	40	ПŠ
tPZL	DIR			3	9 60	30	45	nş
<sup>‡</sup> PHZ	G			2	3 35	28	45	ns
tPLZ	G	AorB	RL=667Ω, CL=5pF,	2	2 35	22	35	ns
TPHZ	DIR	AUFB	See Note 2	2	0 30	24	35	nŝ
<sup>t</sup> PLZ	) Jin			1	9 30	19	30	ns

<sup>&</sup>lt;sup>†</sup> These parameters are measured with the internal output state of the storage register opposite to that of the input. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



# SN54LS647, SN54LS649, SN74LS647, SN74LS649 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH OPEN-COLLECTOR OUTPUTS

SDLS190A - DECEMBER 1982 - REVISED MAY 2004

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Input voltage (control inputs)	
	5.5 V
Operating free-air temperature range: SN54LS647,	SN54LS649 – 55°C to 125°C
SN74LS647,	$5N74LS649 \dots -0^{\circ}C$ to $70^{\circ}C$
Storage temperature range	$-65^{\circ}$ C to $150^{\circ}$ C

### recommended operating conditions

				N64LS6		SN74LS647			UNIT
			S	SN54LS649			SN74LS649		
			MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage			•	0.5			0.6	V
∨он	High-level output voltage				5.5			5.5	V
OL	Low-level output voltage				12			24	mA
		CBA or CAB high	15			15			
tw	Pulse duration	CBA or CAB low	30			30			ns
		Data high or low	30			30			
t <sub>su</sub>	Setup time before CAB† or CBA†	A or B	15			15			ns
•	Hold time	A B			-	_			
th after CAB† or CBA†		A or B	0			0			ns ns
$T_A$	Operating free-air tempera	ure	- 55		125	0	_	70	°c

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS <sup>†</sup>			SN54LS647 SN54LS649			SN74LS647 SN74LS649		
			MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V <sub>IK</sub>		V <sub>CC</sub> = MIN, I <sub>1</sub> = - 18 mA				- 1.5			- 1.5	٧
Hysteresis (V <sub>T+</sub> -V <sub>T-</sub> )	A or B input	V <sub>CC</sub> = MIN		0.1	0.4		0.2	0.4		٧
łон		V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, V <sub>OH</sub> = 5.5 V	VIL = MAX,			0.1			0.1	mA
Vai		VCC = MIN, VIH = 2 V,	I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	V
VOL		VIL = MAX	IOL = 24 mA	1				0.35	0.5	V
1,	A or B	V <sub>CC</sub> = MAX	V <sub>1</sub> = 5.5 V			0.1	0.1			mA
11	All others	CC - MAX	V1 = 7 V			0.1		0.1		
ЧН		V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V				20			20	μΑ
HL		V <sub>CC</sub> = MAX, V <sub>1</sub> = 0.4 V				- 0.4	Γ		- 0.4	mA
	'LS647	)/MAY Output	Outputs high		79	130		79	130	
¹cc -	L904/ VCC = /	V <sub>CC</sub> = MAX, Outputs open	Outputs low		94	150	I	94	150	
	'LS649	VCC = MAX, Outputs open	Outputs high		79	130		79	130	m A
	20049	VCC - MAX, Outputs open	Outputs low		94	150		94	150	

 $<sup>^\</sup>dagger$  For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



I All typical values are at  $V_{CC}$  = 5 V,  $T_{A}$  = 25° C.

# SN54LS647, SN54LS649, SN74LS647, SN74LS649 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH OPEN-COLLECTOR OUTPUTS SDLS190A - DECEMBER 1982 - REVISED MAY 2004

# switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C

PARAMETER	FROM	TO	TEST COMPLETIONS		'LS647			L\$649		
TATAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	TINU
†PLH	CAB or CBA	A or B			22	35		17	30	ns
t <sub>PHL</sub>	CAB OF CBA	AOIB			28	45		28	45	กร
tPLH	AprB	B or A			17	26		15	25	ns
<sup>t</sup> PHL	70.0	B 01 A	f		18	27		20	30	ns
<sup>t</sup> PLH	SAB or SBAT				33	50	_	37	55	ns
<sup>t</sup> PHL	with Bus input high	A or B	RL=667Ω, CL=45pF,		29	45		28	45	ns
†PLH	SAB or SBAT	A Or B	See Note 2		39	60		30	45	ns
<sup>t</sup> PHL	with Bus input low				19	30		26	40	ns
<sup>‡</sup> PLH	G				25	40		21	40	ns
<sup>t</sup> PHL	"	A B			33	50		34	50	ns
tPLH_	DIR	A or B	m.		23	35		19	30	ns
<sup>T</sup> PHL					25	40		27	45	ns

 $<sup>^{\</sup>dagger}$  These parameters are measured with the internal outputs state of the storage register opposite to that of the bus input. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



### PACKAGE OPTION ADDENDUM





### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LS646DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS646DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS646DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS646DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS646DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS646DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS646NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS646NT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS646NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS647DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN74LS647NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS648DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS648DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS648DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS648NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS648NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS649NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder



### PACKAGE OPTION ADDENDUM

18-Sep-2008

temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS646DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1





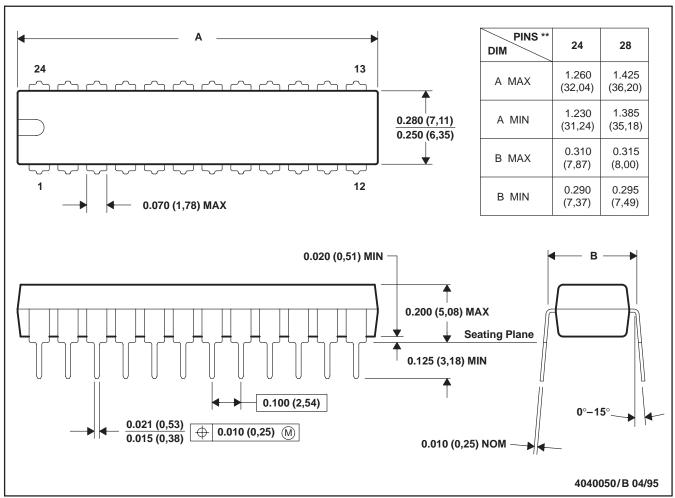
### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS646DWR	SOIC	DW	24	2000	346.0	346.0	41.0

### NT (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

### **24 PINS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

# DW (R-PDSO-G24)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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